- ZZI These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

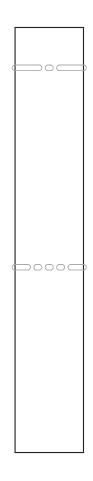


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

100

PCB VIEWED FROM TOP SIDE		BOARD #:	TIDA-00752	REV: EI	SUN REU:	Not In VersionControl
LAYER NAME = Assembly Top		TID #:	TIDA-00752			
PLOT NAME =	Top Assembly Drawing	GENERATED :	12/9/2015	21 281 22 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00752	REV: E1	SUN REU	: Not In VersionControl		
	TID #: TIDA-00752					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/9/20	15 2: 28: 23	PM	TEXAS INSTRUMENTS		

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